



## A3L:25DT.XXI

### VOLTAGE RATINGS

Part Number	V <sub>RRM</sub> , V <sub>R</sub> (V)		Max. non-rep. peak reverse voltage
	T <sub>J</sub> = 0 to 125°C	T <sub>J</sub> = -40 to 0°C	
A3L:25TD.02I	200	200	300
A3L:25TD.04I	400	400	500
A3L:25TD.06I	600	600	700
A3L:25TD.08I	800	800	900
A3L:25TD.10I	1000	1000	1100
A3L:25TD.12I	1200	1200	1300
A3L:25TD.14I	1400	1330	1500
A3L:25TD.16I	1600	1520	1700

### MAXIMUM ALLOWABLE RATINGS

PARAMETER	VALUE	UNITS	NOTES
T <sub>J</sub> Junction Temperature	-40 to 125	°C	-
T <sub>stg</sub> Storage Temperature	-40 to 150	°C	-
I <sub>F(AV)</sub> Max. Av. current @ Max. T <sub>C</sub>	25 85	A °C	180° half sine wave
I <sub>F(RMS)</sub> Nom. RMS current	55	A	-
I <sub>FSM</sub> Max. Peak non-rep. surge current	0.5 0.54 0.57 0.62	kA	50 Hz half cycle sine wave Initial T <sub>J</sub> = 125°C, rated V <sub>RRM</sub> applied after surge. 60 Hz half cycle sine wave 50 Hz half cycle sine wave Initial T <sub>J</sub> = 125°C, no voltage applied after surge. 60 Hz half cycle sine wave
I <sup>2</sup> t Max. I <sup>2</sup> t capability	1.3 1.41 1.48 1.61	kA <sup>2</sup> s	t = 10ms Initial T <sub>J</sub> = 125°C, rated V <sub>RRM</sub> applied after surge. t = 8.3 ms t = 10ms Initial T <sub>J</sub> = 125°C, no voltage applied after surge. t = 8.3 ms
I <sup>2</sup> t <sup>1/2</sup> Max. I <sup>2</sup> t <sup>1/2</sup> capability	17.7	kA <sup>2</sup> s <sup>1/2</sup>	Initial T <sub>J</sub> = 125°C, no voltage applied after surge. $t_x = I^2 t^{1/2} * t_x^{1/2}$ . (0.1 < t <sub>x</sub> < 10ms).
di/dt Max. Non-repetitive rate-of-rise current	500	A/μs	T <sub>J</sub> = 125°C, V <sub>D</sub> = V <sub>DRM</sub> , I <sub>TM</sub> = 1600A. Gate pulse: 20V, 20Ω, 10μs, 0.5μs rise time, Max. repetitive di/dt is approximately 40% of non-repetitive value.
P <sub>GM</sub> Max. Peak gate power	10	W	tp < 5 ms
P <sub>G(AV)</sub> Max. Av. gate power	3	W	-
+I <sub>GM</sub> Max. Peak gate current	150	mA	tp < 5 ms
-V <sub>GM</sub> Max. Peak negative gate voltage	2	V	-
F Mounting Force	3(5)	N.m	Upper connectors(Heatsink)

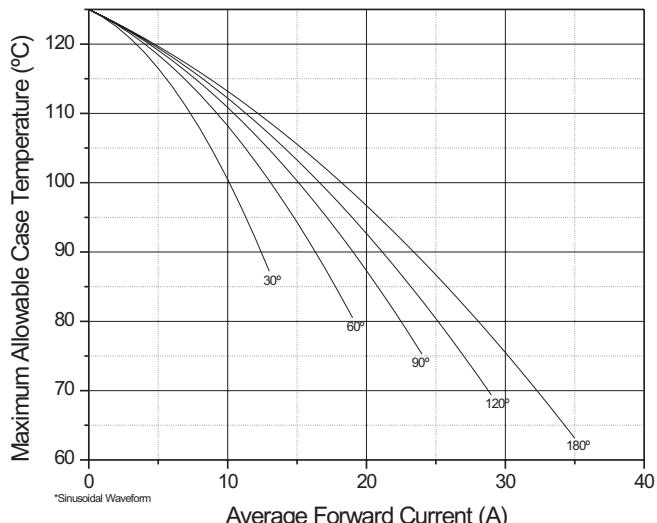


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### CHARACTERISTICS

PARAMETER	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
$V_{TM}$ peak on-state voltage	---	---	2	V	Initial $T_J = 25^\circ\text{C}$ , 50-60Hz half sine, $I_{peak} = 79\text{A}$ .
$V_{T(TO)}$ Threshold voltage	---	---	0.95	V	$T_J = 125^\circ\text{C}$ Av. power = $V_{T(TO)} * I_{T(AV)} + r_T * [I_{T(RMS)}]^2$ , 180 Half Sine.
$r_T$ Slope resistance	---	---	12.6	$\text{m}\Omega$	Use low values for $I_{TM} < \pi$ rated $I_{T(AV)}$
$I_L$ Latching current	---	---	400	mA	$T_C = 125^\circ\text{C}$ , 12V anode. Gate pulse: 10V, $20\Omega$ , $100\mu\text{s}$ .
$I_H$ Holding current	---	---	200	mA	$T_C = 25^\circ\text{C}$ , 12V anode. Initial $I_T = 15\text{A}$ .
$t_d$ Delay time	---	0.7	1.5	$\mu\text{s}$	$T_C = 25^\circ\text{C}$ , $V_D = V_{DRM}$ , 50A resistive load. Gate pulse: 10V, $20\Omega$ , $10\mu\text{s}$ , $1\mu\text{s}$ rise time.
$t_q$ Turn-off time	---	125	200	$\mu\text{s}$	$T_J = 125^\circ\text{C}$ , $I_{TM} = 500\text{A}$ , $di/dt = 25\text{A}/\mu\text{s}$ , $V_R = 50\text{V}$ . $dv/dt = 20\text{V}/\mu\text{s}$ lin. to rated $V_{DRM}$ . Gate: 0V, $100\Omega$ .
dv/dt Critical rate-of-rise of off-state voltage	80	140	500	$\text{V}/\mu\text{s}$	$T_J = 125^\circ\text{C}$ . Exp. to 100% or lin. Higher dv/dt values To 80% $V_{DRM}$ , gate open. available.
	---	---	250		$T_J = 125^\circ\text{C}$ , Exp. To 67% $V_{DRM}$ , gate open.
$I_{RM}, I_{DM}$ Peak reverse and off-state current	---	10	15	mA	$T_J = 125^\circ\text{C}$ , Rated $V_{RRM}$ and $V_{DRM}$ , gate open.
$I_{GT}$ DC gate current to trigger	---	---	300	mA	$T_C = -40^\circ\text{C}$
	50	80	150		$T_C = 25^\circ\text{C}$ +12V anode-to-cathode. For recommended
$V_{GT}$ DC gate voltage to trigger	4	---	---	V	$T_C = -40^\circ\text{C}$ gate drive see "Gate Characteristics" figure.
	2	---	2.5		$T_C = 25^\circ\text{C}$
$V_{GD}$ DC gate voltage not to trigger	---	---	0.2	V	$T_C = 25^\circ\text{C}$ , Max. Value which will not trigger with rated $V_{DRM}$ anode.
$R_{thJC}$ Thermal resistance, junction-to-case	---	---	0.4	$^\circ\text{C}/\text{W}$	DC operation, single side cooled.
	---	---	0.463	$^\circ\text{C}/\text{W}$	180 sine wave, single side cooled.
	---	---	0.491	$^\circ\text{C}/\text{W}$	120 rectangular wave, single side cooled.
$R_{thCS}$ Thermal resistance, case-to-sink	---	---	0.1	$^\circ\text{C}/\text{W}$	Mtg. Surface smooth, flat and greased. Single side cooled.
wt Weight	---	110(4)	---	g(oz.)	---
Case Style	TO-240AA		JEDEC	---	

Maximum Allowable Case Temperature



Maximum Allowable Case Temperature

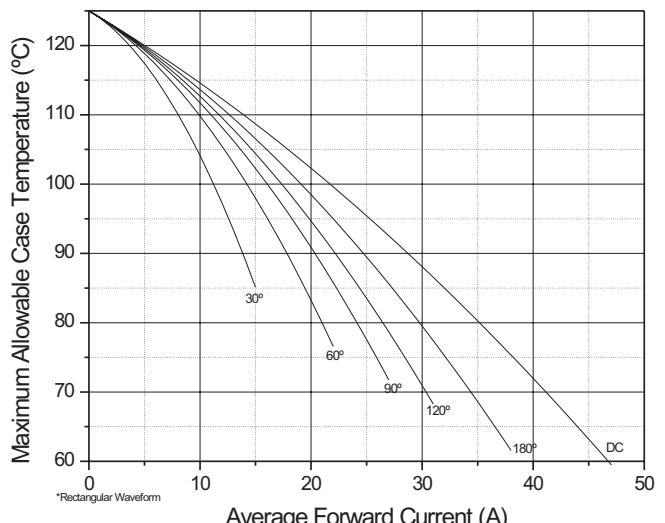


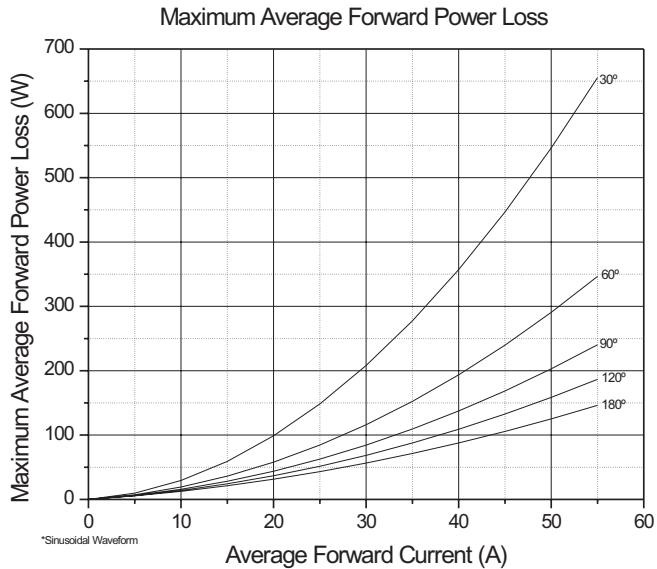
Fig. 1 - Current Ratings Characteristics

Fig. 2 - Current Ratings Characteristics

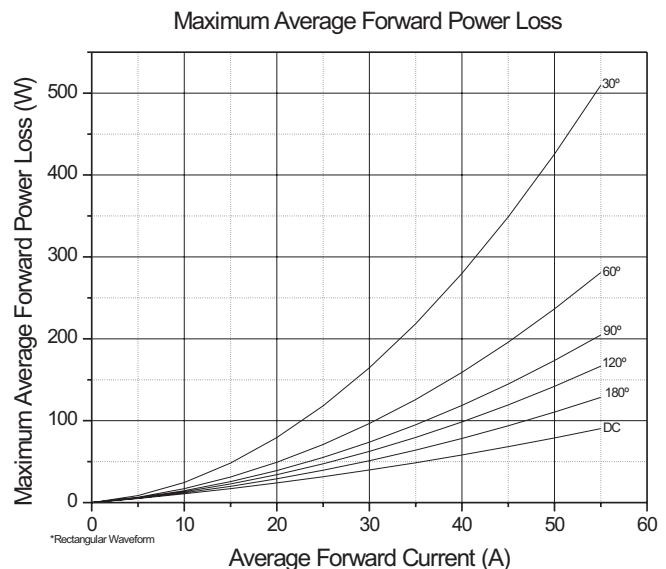


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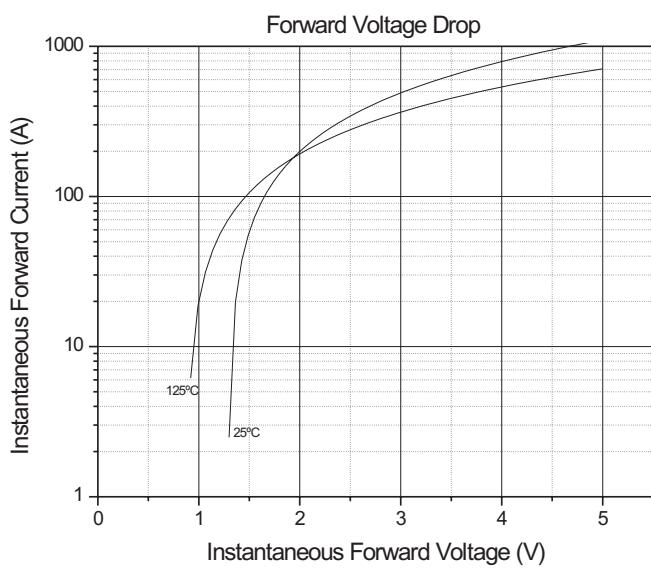
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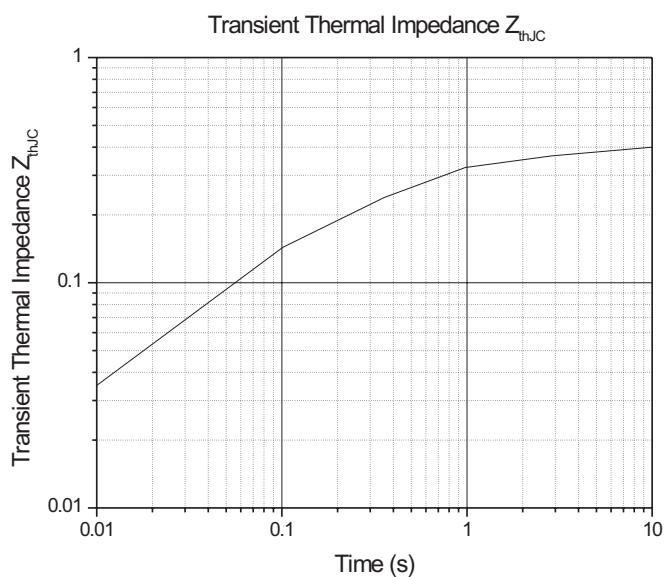
**Fig.3 -Forward Power Loss Characteristics**



**Fig. 4 - Forward Power Loss Characteristics**



**Fig. 5 - Forward Voltage Drop Characteristics**

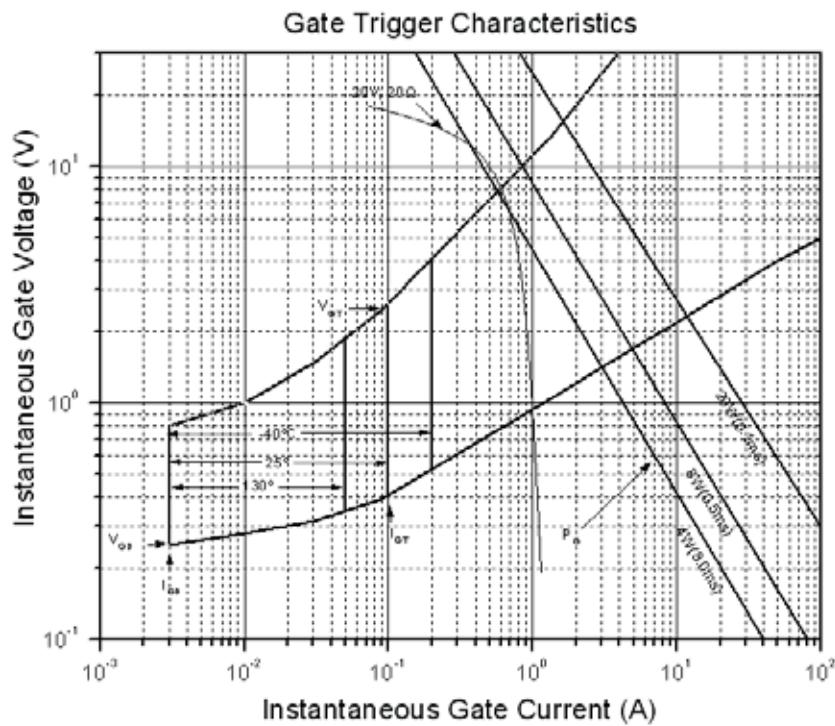


**Fig. 6 - Transient Thermal Impedance**



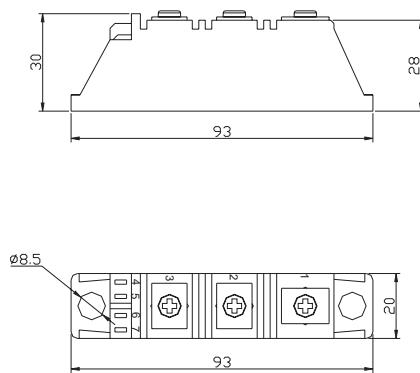
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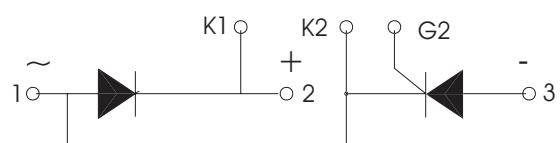


**Fig. 7 - Gate Trigger Characteristics**

## TO-240AA



**Fig. 8 - Outline Characteristics**



**Fig. 9 - Circuit Layout**